	connectors	5
	SPECIFICATION	
宏致	電子股份有限	<b></b> 提公司
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	No.13, Dongyuan Rd., Jhongli Cit	γ,
7	Taoyuan County 320, Taiwan (R.O.	C.)
	TEL: +886-3-463-2808 FAX: +886-3-463-1800	
SPEC. NO.: PS-51645	5-XXXXX-XXX REV	ISION: O
PRODUCT NAME:	).5 mm PITCH EASY ON FPC C	ONN.
	SMT R/A B/C TYPE	
PRODUCT NO: 5	51645 SERIES	
PREPARED:	CHECKED:	APPROVED:
ZHUWEI	BRAVE	FRANK
DATE: 2015/07/28	DATE: 2015/07/28	DATE: 2015/07/28
		<u> </u>

Connectors	Aces P/N: 51645 series	
TITLE: FPC 0.5 PITCH	EASY ON FPC CONN	
RELEASE DATE: 2015/07/28	REVISION: O ECN No: ECN-1507418	PAGE: 2 OF 11
<ul> <li>2 SCOPE</li> <li>3 APPLICABLE DO</li> <li>4 REQUIREMENTS</li> <li>5 PERFORMANCE</li> <li>6 INFRARED REFI</li> <li>7 PRODUCT QUAI</li> </ul>	DRY DCUMENTS S LOW CONDITION LIFICATION AND TEST SEQUENCE IPON USAGE	4 4 4 5 8 9

ICES	Aces P/N: 51645 series
TITLE: FPC 0.5 PITCH EASY ON FP	CCONN

RELEASE DATE: 2015/07/28 REVISION: O

ECN No: ECN-1507418

PAGE: 3 OF 11

## 1 Revision History

Rev.	ECN #	Revision Description	Prepared	Date
0	ECN-1507418	FOR APD1030104 ADD 51645 SPEC	ZHUWEI	2015/7/28
I				

1	CES			Aces P/N:	51645 series		
Т	ITLE: FPC 0	.5 PITCH	EASY ON FI	PC CONN			
REL	EASE DATE: 2015	6/07/28	REVISION: 0		ECN No: ECN-1507	418	PAGE: 4 OF 11
2			overs perform		and quality requ	irements for (	0.5mm pitch
3	<b>APPLICAE</b> EIA-364:		CUMENTS	RIES ASSO	CIATION		
4	REQUIREI	MENTS					
	4.1 Design a	nd Constru	uction				
	4.1.1 4.1.2	applicable	e product draw	ng.	on and physical d I the standard dep	-	
	4.2 Materials	and Finis	า				
	4.2.2 H 4.2.3 /	-inish: Housing: T Actuator: T	(a) Contact Ar (b) Under plate (c) Solder area hermoplastic c hermoplastic c	ea: Refer to e: Refer to th a: Refer to th or Thermopla or Thermopla	e drawing.	JL94V-0	
	4.3 Ratings						
	4.3.2 4.3.3	Voltage: 4 Current: 0	oltage less that 50 Volts AC (pe ).5 Amperes ( Temperature :	er pin) per pin)			
				Page 4		2010/10/31	TR-FM-73015

Ces		Aces P/N: 5	1645 series	
TITLE: FPC 0.5 PITCH	I EASY ON FF	PC CONN		
RELEASE DATE: 2015/07/28	REVISION: 0		ECN No: ECN-1507418	PAGE: 5 OF 11

# 5 Performance

# 5.1. Test Requirements and Procedures Summary

Item	Requirement	Standard
Examination of Product	Product shall meet requirements of applicable product drawing and specification.	
	ELECTRICAL	
ltem	Requirement	Standard
Low Level Contact Resistance	50 m Ω Max. (initial)per contact 20 m Ω Max. change allowed	Mate connectors, measure by dry circuit, 20mV Max., 100mA Max. (EIA-364-23)
Insulation Resistance	500 M Ω Min.	Unmated connectors, apply 500 V DC between adjacent terminals. (EIA-364-21)
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 1 mA max.	300 VAC Min. at sea level for 1 minute. Test between adjacent contacts of unmated connectors. (EIA-364-20)
Temperature Rise	30℃ Max. Change allowed	Mate connector: measure the temperature rise at rated current until temperature stable. The ambient condition is still air at 25°C (EIA-364-70, METHOD1,CONDITION1)

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### Aces P/N: 51645 series

### TITLE: FPC 0.5 PITCH EASY ON FPC CONN

RELEASE DATE: 2015/07/28 REVISION: O

ECN No: ECN-1507418

PAGE: 6 OF 11

	MECHANICA	L
ltem	Requirement	Standard
Durability	30 cycles.	The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of 25.4 ± 3mm/min. (EIA-364-09)
PC Retention Force erminal / Housing etention Force itting Nail /Housing etention Force	30gf/PIN MIN.	A connector shall be soldered on a board and insert the actuator, pull the FPC at the speed rate of $25.4 \pm$ 3 mm/min.
Terminal / Housing Retention Force	100 gf MIN.	Operation Speed : 25.4 ± 3 mm/minute. Measure the contact retention force with tester.
Fitting Nail /Housing Retention Force	100 gf MIN.	Operation Speed : $25.4 \pm 3$ mm/minute. Measure the contact retention force with tester.
Vibration	1 μs Max.	The electrical load condition shall be 100 mA maximum for all contacts. Subject to a simple harmonic motion having amplitude of 0.76mm (1.52mm maximum total excursion) in frequency between the limits of 10 and 55 Hz. The entire frequency range, from 10 to 55 Hz and return to 10 Hz, shall be traversed in approximately 1 minute. This motion shall be applied for 2 hours in each of three mutually perpendicular directions. (EIA-364-28 Condition I)
Shock (Mechanical)	1 μs Max.	Subject mated connectors to 50 G's (peak value) half-sine shock pulses of 11 milliseconds duration. Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks). The electrical load condition shall be 100mA maximum for all contacts. (EIA-364-27, test condition A)

ACES

### Aces P/N: 51645 series

### TITLE: FPC 0.5 PITCH EASY ON FPC CONN

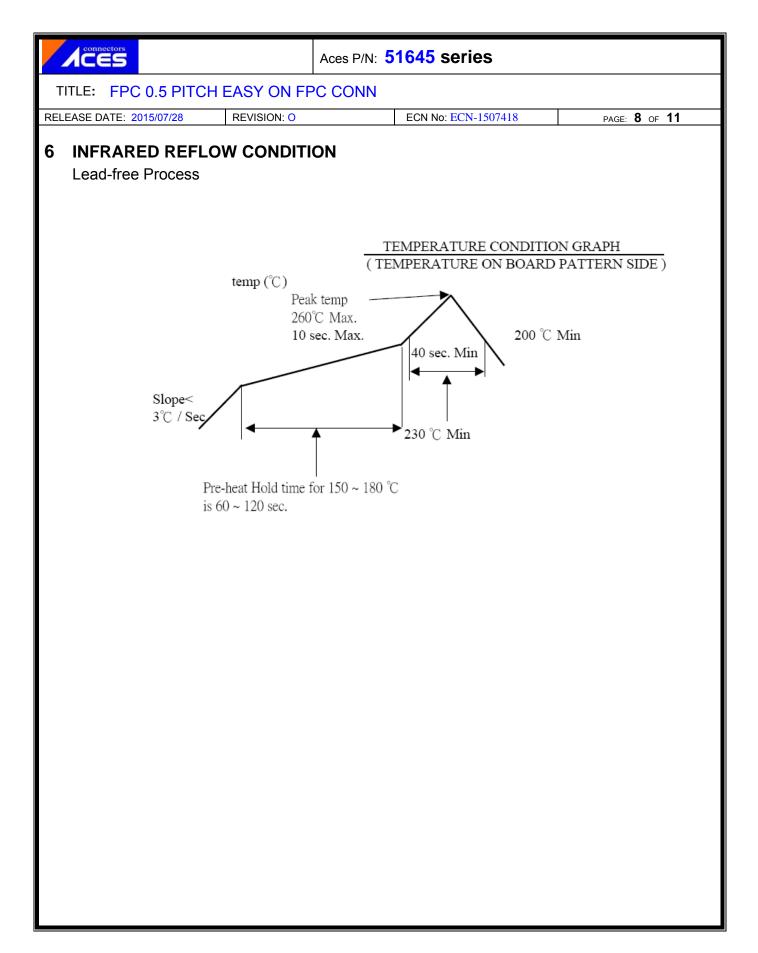
RELEASE DATE: 2015/07/28 REVISION: O

ECN No: ECN-1507418

PAGE: 7 OF 11

Item	Requirement	Standard			
Resistance to <b>Reflow</b> Soldering Heat	See Product Qualification and Test Sequence Group 10 <b>(Lead Free)</b>	Pre Heat : 150°C∼180°C, 60~120sec. Heat : 230°C Min., 40sec Min. Peak Temp. : 260°C Max, 10sec Max. Reflow number cycle: 2 times (EIA-364-56)			
Hand Soldering Temperature Resistance	Appearance: No damage	T≧350°C, 5sec at least.			
Thermal Shock	See Product Qualification and Test Sequence Group 4	-40 +0/-3 ℃, 30 minutes +85 +3/-0 ℃, 30 minutes (EIA-364-32, test condition I)			
Humidity	See Product Qualification and Test Sequence Group 4	Mated Connector 40°C, 90~95% RH, 96 hours. (EIA-364-31,Condition A, Method II)			
Temperature life	See Product Qualification and Test Sequence Group 5	Subject mated connectors to temperature life at 85°C for 96 hours. (EIA-364-17, Test condition A)			
Salt Spray (Only For Gold Plating)	See Product Qualification and Test Sequence Group 6	Subject mated/unmated connectors to 5% salt-solution			
Solder ability	Tin plating: Solder able area shall have minimum of 95% solder coverage. Gold plating: Solder able area shall have minimum of 75% solder coverage	And then into solder bath, Temperature at 245 ±5℃, for 4-5 sec. (EIA-364-52)			
Resistance to <b>Wave</b> Soldering Heat	See Product Qualification and Test Sequence Group 10 (Lead Free)	Solder Temp. ∶ 265±5℃, 10±0.5sec.			

Note. Flowing Mixed Gas shell be conduct by customer request.



CES	Aces F	P/N: 5	1645	ser	ies					
ITLE: FPC 0.5 PITCH EASY ON FP		NN								
EASE DATE: 2015/07/28 REVISION: O			ECN	No: ECI	N-15074	18		PA	GE: <b>9</b>	of <b>11</b>
PRODUCT QUALIFICATION A	ND TE	ST S	EQU	ENC	E					
	Test Group									
Test or Examination	1	2	3	4	5	6	7	8	9	10
				Т	est Se	quenc	e		I	
Examination of Product	1、3	1 • 8	1 • 7	1、6	1、4				1	
Low Level Contact Resistance		2、11	2、10	2 • 9	2 \ 5				3	1、4
Insulation Resistance		3、10	3、9	3、8						
Dielectric Withstanding Voltage		4 • 9	4 • 8	4 \ 7						
Temperature rise	2									
Durability		6								
Vibration										2
Shock (Mechanical)										3
Thermal Shock			5							
Humidity			6							
Temperature life				5						
Salt Spray					3					
Solder ability						1				
FPC Retention Force		5 \ 7								
Terminal / Housing Retention Force							1			
Fitting Nail /Housing Retention Force								1		
Resistance to Soldering Heat									2	
Sample Size	2	4	4	4	4	2	4	4	4	4

